

U.S. Patent Application Serial No. 09/805,559
Amendment dated July 31, 2003
Reply to the Office Action of March 4, 2003

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 - 5 (canceled)

Claim 6 (Currently Amended): A structure comprising:

a semiconductor device having bumps;

a board having pads so that each of the bumps is joined to a corresponding one of the pads, each of the pads per se having a ~~concave~~ deformed surface with which a corresponding one of the bumps contacts; and

an insulating adhesive provided between the semiconductor device and the board, and in contact with each of the pads and bumps wherein

an end of each of the bumps has a diameter smaller than other portions of the bumps so as to facilitate deformation of the pad when bumps are pressed against the pads and to form a space in which the insulating adhesive is filled, and wherein

contraction of the insulating adhesive maintains joints of the bumps and the pads, said joints being made by deformation of the pads.

Claims 7 - 11 (canceled)
